



Material Content Data Sheet



Sales Product Name		SAB-C161S-L25M AA		Issued		29. August 2013		
MA#		MA000455288						
Package		PG-MQFP-80-7		Weight*		989.78 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	17.388	1.76	1.76	17568	17568
leadframe	non noble metal	magnesium	7439-95-4	0.375	0.04		379	
	inorganic material	silicon	7440-21-3	1.624	0.16		1641	
	non noble metal	nickel	7440-02-0	7.494	0.76		7572	
	non noble metal	copper	7440-50-8	240.318	24.28	25.24	242799	252391
wire	noble metal	gold	7440-57-5	3.798	0.38	0.38	3837	3837
encapsulation	organic material	carbon black	1333-86-4	2.096	0.21		2118	
	plastics	epoxy resin	-	88.730	8.96		89646	
	inorganic material	silicondioxide	60676-86-0	607.836	61.42	70.59	614113	705877
leadfinish	non noble metal	tin	7440-31-5	9.487	0.96	0.96	9585	9585
plating	noble metal	silver	7440-22-4	7.024	0.71	0.71	7096	7096
glue	plastics	acrylic resin	-	0.722	0.07		729	
	noble metal	silver	7440-22-4	2.887	0.29	0.36	2917	3646
*deviation	< 10%					Sum in total:	100,00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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